

Discover the Future of Test and Inspection



BOOTH 1134

Keeping up with the pace of innovation in the EMS industry calls for ground-breaking solutions and cutting-edge know-how. TRI brings both to IPC APEX 2016 with all-new SPI, AOI, ICT and AXI solutions for the most reliable PCB Assembly test and inspection portfolio in the industry.

Visit booth #1134 for a personal tour of PCB assembly future!

3D SPI

TR7007QI Digital Fringe Pattern 3D SPI

Ultra-high precision solder paste inspection ready for the latest 008004in micro-components, breaking the 10 µm barrier.



3D AOI

TR7700QI Digital Fringe Pattern 3D AOI

Advanced 3D AOI with accurate solder fillet inspection and adaptive 3D height range for future-proof inspection performance.



3D CT AXI

TR7600 SII CT Advanced 3D X-ray Inspection with CT

High speed 3D X-ray inspection reveals solder joint quality and with superb image quality using Planar 3D Computed Tomography.



Parallel ICT

TR5001 SII INLINE Multi-core Parallel ICT

Flexible test platform offering up to 4096 hybrid test points and dual/quad core parallel test options.



YMS 4.0 Yield Management System



Upgrade your inspection with Industry 4.0!

TR7500 SIII 3D High Performance 3D AOI



Industry-leading 3D Inspection speed and range!

TR5001 SII TINY Parallel TINY ICT



PCBA testing in a powerful, portable package!

TR7007 SII Plus High Performance 3D SPI



Industry-leading Inspection speed and accuracy!



LAS VEGAS/NEVADA

LAS VEGAS CONVENTION CENTER
CONFERENCE & EXHIBITION: **March 15-17**

TRI INSPECTION AT BOOTH: **1134**

RESERVE A PRIVATE DEMO AT TRI BOOTH: triusa@tri.com.tw